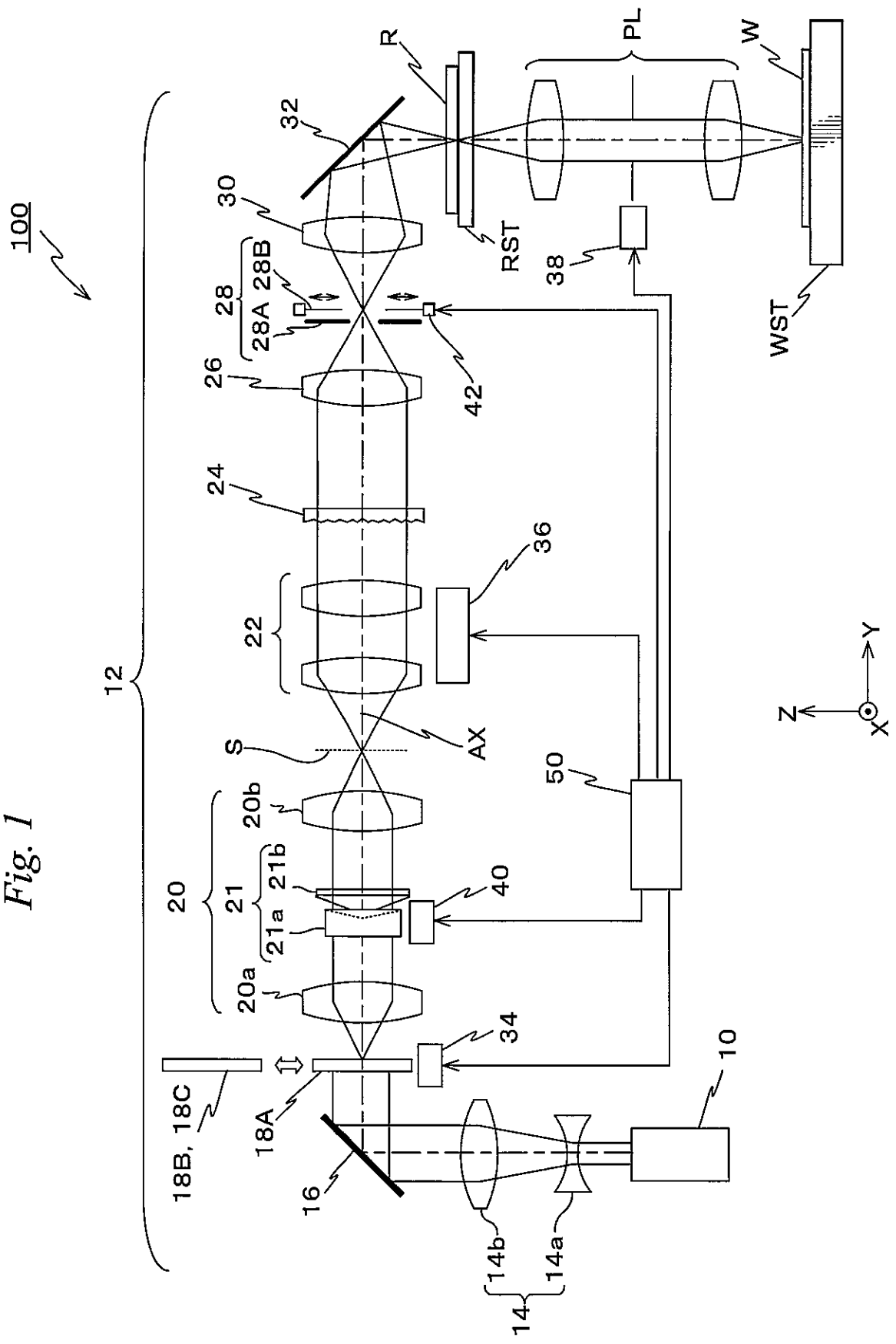
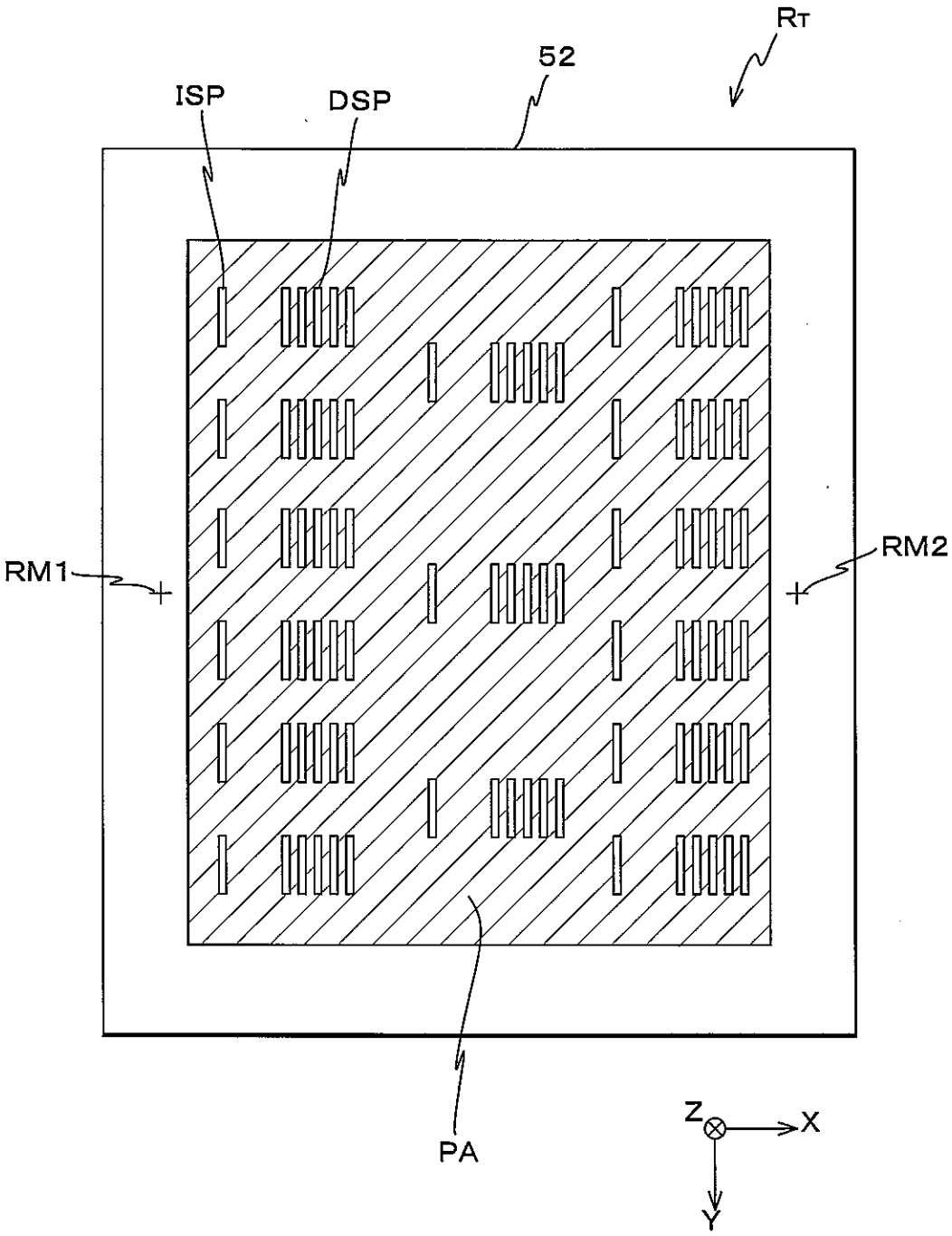

100
12
R
PL
W
32
30
RST
38
WST
28
28A
28B
42
26
24
36
22
S
AX
50
20
20b
21
21b
21a
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34
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18B, 18C
18A
16
14b
14a
14
Y
Z
X

Fig. 1

Fig. 2



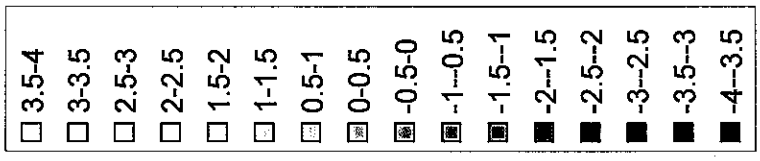


Fig. 3A

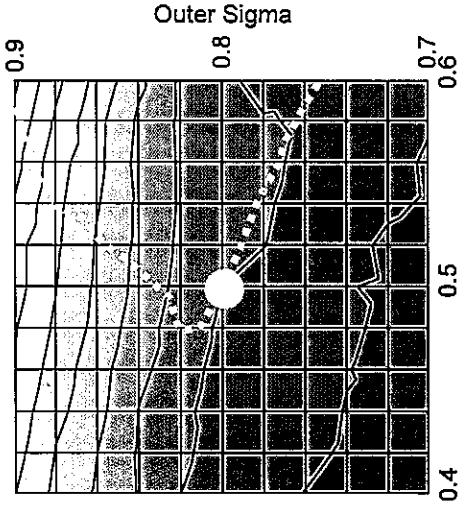


Fig. 3B

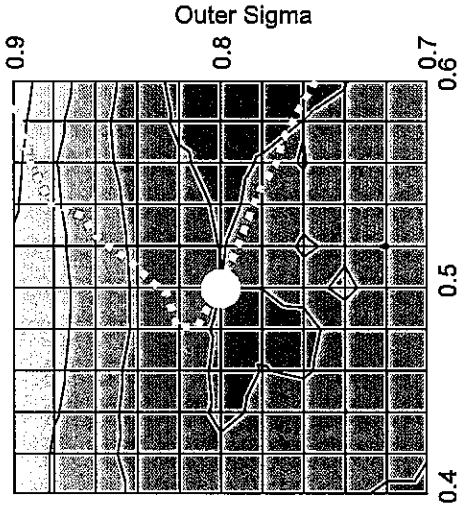


Fig. 3C

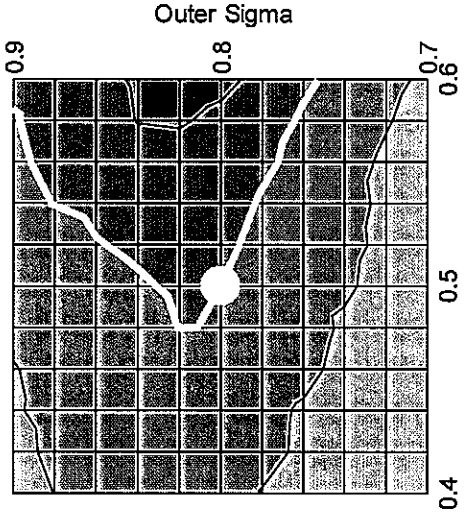


Fig. 3D

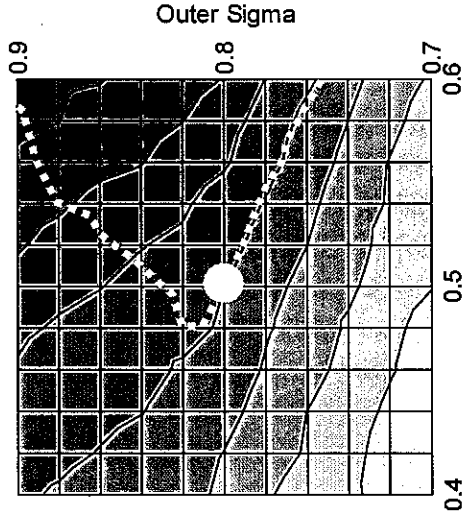


Fig. 3E

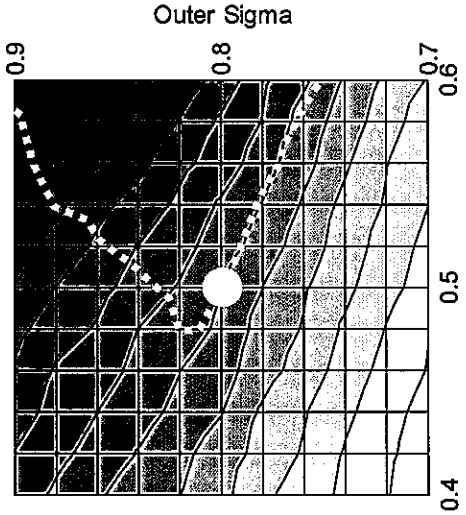


Fig. 3F

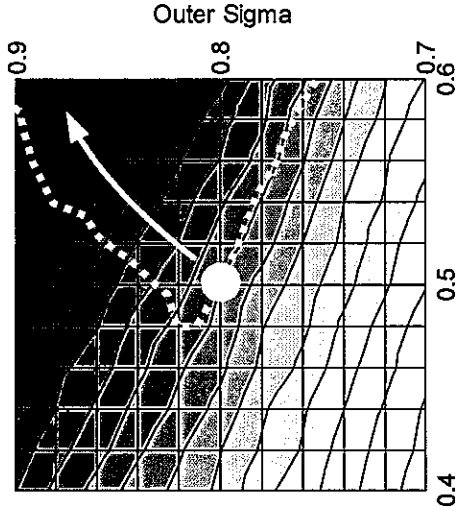


Fig. 4

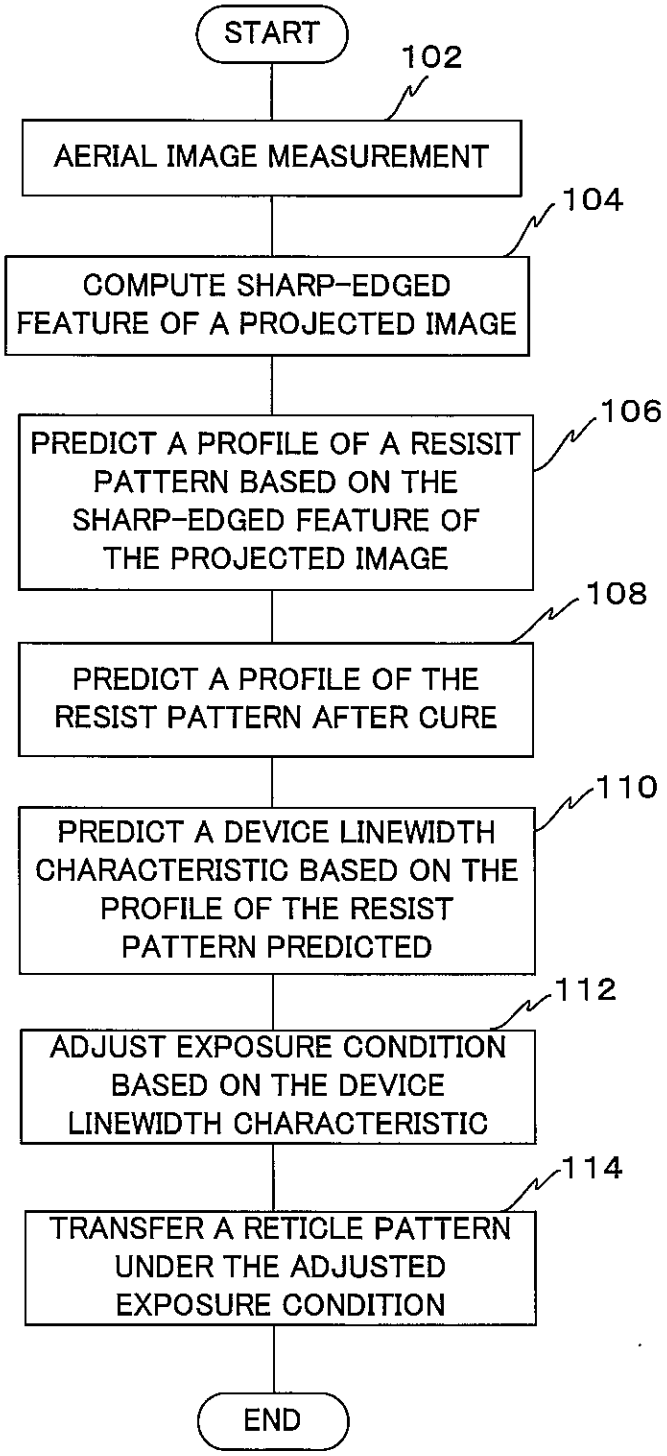

START
102
AERIAL IMAGE MEASUREMENT
104
COMPUTE SHARP-EDGED FEATURE OF A PROJECTED IMAGE
106
PREDICT A PROFILE OF A RESISIT PATTERN BASED ON THE SHARP-EDGED FEATURE OF THE PROJECTED IMAGE
108
PREDICT A PROFILE OF THE RESIST PATTERN AFTER CURE
110
PREDICT A DEVICE LINEWIDTH CHARACTERISTIC BASED ON THE PROFILE OF THE RESIST PATTERN PREDICTED
112
ADJUST EXPOSURE CONDITION BASED ON THE DEVICE LINEWIDTH CHARACTERISTIC
114
TRANSFER A RETICLE PATTERN UNDER THE ADJUSTED EXPOSURE CONDITION
END

Fig. 5A

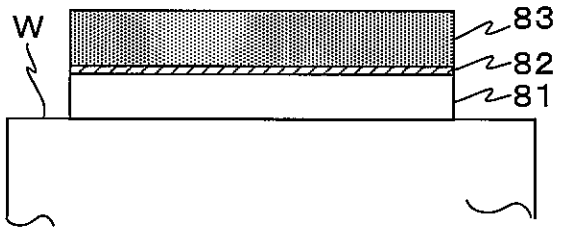


Fig. 5B

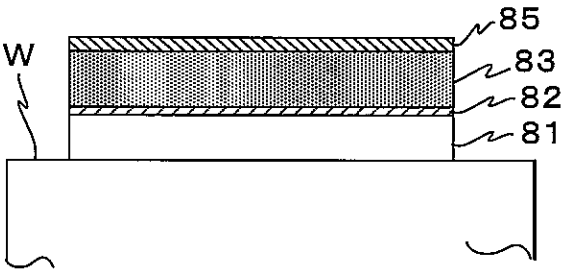


Fig. 5C

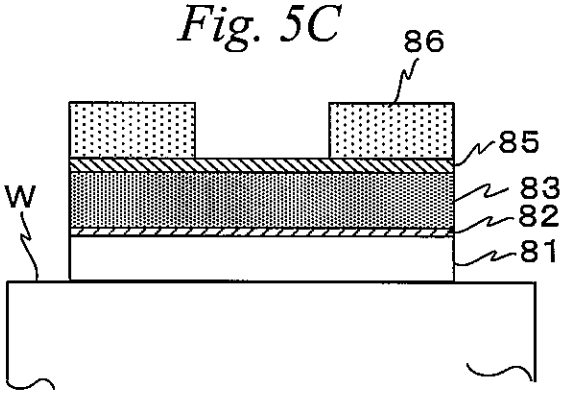


Fig. 5D

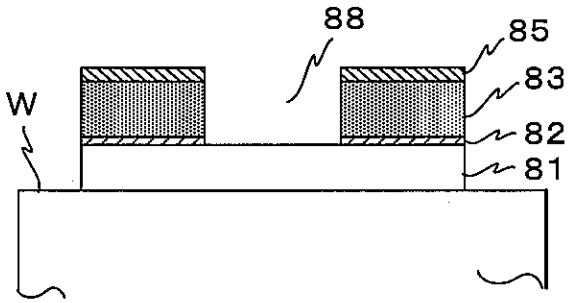


Fig. 5E

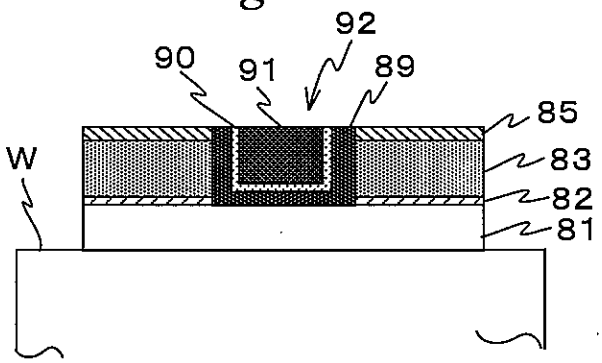


Fig. 6A

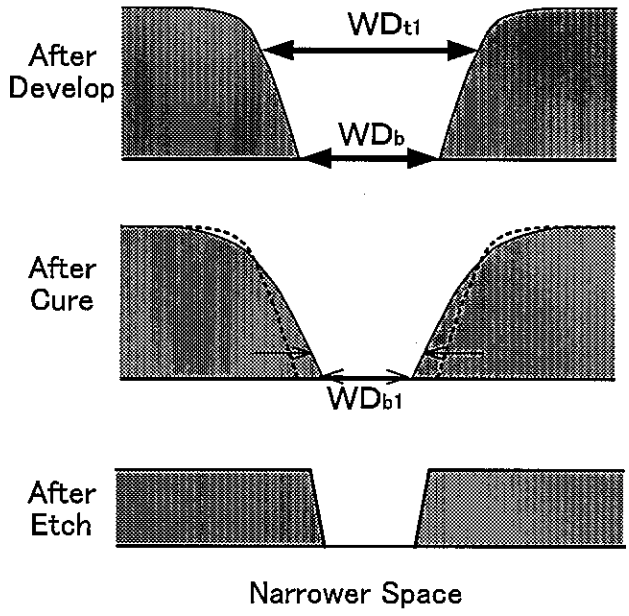


Fig. 6B

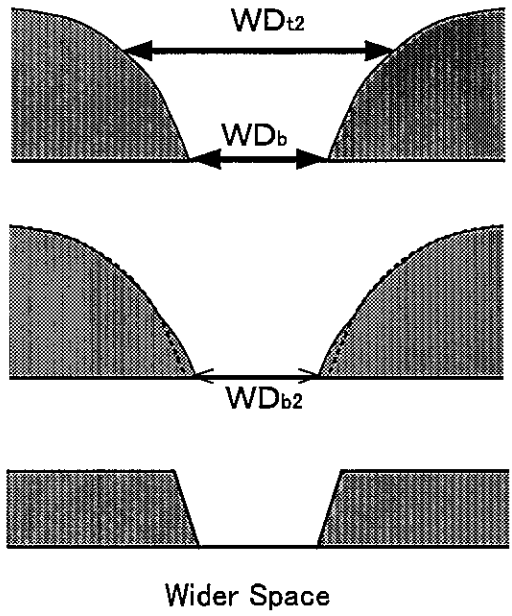


Fig. 7A

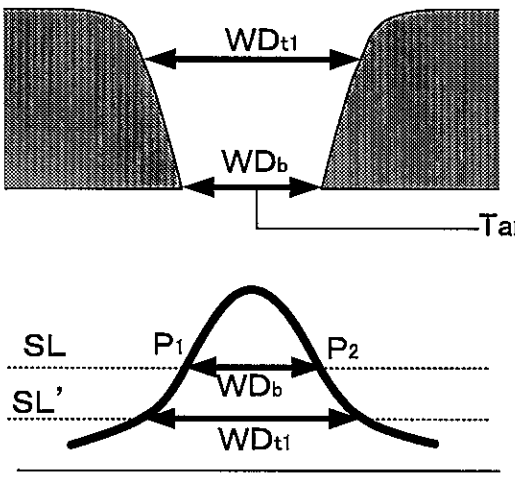


Fig. 7B

